Compliant with IEC 62474/ D9.00 Compliant to IEC 61249-2-21:2003

MICROCHIP  Semiconductor Device Type: H6A 004 VDFN 3.2x5.0x0.9mm NiPdAu			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)				J-STD-609A Product Marking and/or Pkg. Labeling e4
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	24.86	(mg) Total	Mold Compound	% ot Total Weight	60.63
Silica, fused	60676-86-0	Mold Compound	54.567	22.372	545.670		Silica, fused	60676-86-0	90.00	
Epoxy Resin	Trade Secret	Mold Compound	2.941	1,206	29.406		Epoxy Resin	Trade Secret	4.85	
Phenolic Resin	Trade Secret	Mold Compound	2.941	1,206	29,406		Phenolic Resin	Trade Secret	4.85	
Carbon Black	1333-86-4	Mold Compound	0.182	0.075	1,819		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	34.230	14.034	342,301			Total	100.00	
Iron	7439-89-6	Lead Frame	0.809	0.332	8.091	14.42	(mg) Total	Lead Frame	% of Total Weight	35.18
Phosphorous	7723-14-0	Lead Frame	0.088	0.036	880		Copper	7440-50-8	97.30	00.10
Zinc (Metal)	7440-66-6	Lead Frame	0.053	0.022	528		Iron	7439-89-6	2.30	
Silver	7440-22-4	Die Attach	0.375	0.154	3.750		Phosphorous	7723-14-0	0.25	
Methacrylic acid, isobornyl ester	7534-94-3	Die Attach	0.070	0.029	700		Zinc (Metal)	7440-66-6	0.15	
1,3-Bismaleimidobenzene	3006-93-7	Die Attach	0.038	0.015	375			Total	100.00	
polymer with oxirane mono-2-propenoate	1017237-78-3	Die Attach	0.018	0.007	175	0.21	(mg) Total	Die Attach	% of Total Weight	0.50
Silicon	7440-21-3	Chip (Die)	2.000	0.820	20.000	0.21	Silver	7440-22-4	75.00	0.00
Gold	7440-57-5	Wire Bond	0.210	0.086	2.100	M	ethacrylic acid, isobornyl es	7534-94-3	14.00	
Nickel	7440-02-0	Plating on external leads (pins)	1.332	0.546	13.320	IV	1.3-Bismaleimidobenzene	3006-93-7	7.50	
Palladium	7440-05-3	Plating on external leads (pins)	0.074	0.030	740	nolym	er with oxirane mono-2-prop	1017237-78-3	3.50	
						polyili	ci with oxilanc mono z prop	1011201 100	0.00	
		3	0.074	0.020	740			Total	100.00	
Gold	7440-57-5	Plating on external leads (pins)	0.074	0.030	740	0.00	Tatal (mm)	Total	100.00	2.00
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